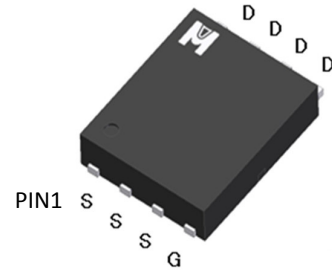
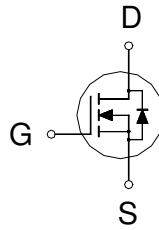


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV _{DSS}	30V
R _{DS(on) (MAX.)}	4.0mΩ
I _D	75A



N Channel MOSFET

UIS, R_g 100% Tested

Pb-Free Lead Plating & Halogen Free

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current	T _C = 25 °C	I _D	75	A
	T _C = 100 °C		45	
Pulsed Drain Current ¹		I _{DM}	160	
Avalanche Current		I _{AS}	53	
Avalanche Energy	L = 0.1mH, I _D =53A, R _G =25Ω	E _{AS}	140	mJ
Repetitive Avalanche Energy ²	L = 0.05mH	E _{AR}	40	
Power Dissipation	T _C = 25 °C	P _D	50	W
	T _C = 100 °C		26	
Operating Junction & Storage Temperature Range		T _J , T _{stg}	-55 to 150	°C

100% UIS testing in condition of V_D=15V, L=0.1mH, V_G=10V, I_L=40A, Rated V_{DS}=30V N-CH

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	R _{θJC}		2.5	°C / W
Junction-to-Ambient	R _{θJA}		50	

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

³50°C / W when mounted on a 1 in² pad of 2 oz copper.



ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT	
			MIN	TYP	MAX		
STATIC							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	30			V	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.0	1.7	3.0		
Gate-Body Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V			±100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V			1	μA	
		V _{DS} = 20V, V _{GS} = 0V, T _J = 125 °C			25		
On-State Drain Current ¹	I _{D(ON)}	V _{DS} = 10V, V _{GS} = 10V	75			A	
Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = 10V, I _D = 30A		3.4	4.0	mΩ	
		V _{GS} = 4.5V, I _D = 24A		4.1	5.0		
Forward Transconductance ¹	g _{fs}	V _{DS} = 5V, I _D = 24A		25		S	
DYNAMIC							
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz		2094		pF	
Output Capacitance	C _{oss}			324			
Reverse Transfer Capacitance	C _{rss}			162			
Gate Resistance	R _g	V _{GS} = 15mV, V _{DS} = 0V, f = 1MHz		2.0		Ω	
Total Gate Charge ^{1,2}	Q _g (V _{GS} =10V)	V _{DS} = 15V, V _{GS} = 10V, I _D = 30A		32		nC	
	Q _g (V _{GS} =4.5V)			14.3			
Gate-Source Charge ^{1,2}	Q _{gs}			7.0			
Gate-Drain Charge ^{1,2}	Q _{gd}			5.9			
Turn-On Delay Time ^{1,2}	t _{d(on)}		V _{DS} = 15V, I _D = 24A, V _{GS} = 10V, R _{GS} = 2.7Ω		15		nS
Rise Time ^{1,2}	t _r				15		
Turn-Off Delay Time ^{1,2}	t _{d(off)}			50			
Fall Time ^{1,2}	t _f			20			
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_c = 25 °C)							
Continuous Current	I _S				75	A	
Pulsed Current ³	I _{SM}				150		
Forward Voltage ¹	V _{SD}	I _F = I _S , V _{GS} = 0V			1.3	V	
Reverse Recovery Time	t _{rr}	I _F = I _S , dI _F /dt = 100A / μS		30		nS	
Peak Reverse Recovery Current	I _{RM(REC)}			200		A	
Reverse Recovery Charge	Q _{rr}			10		nC	

¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

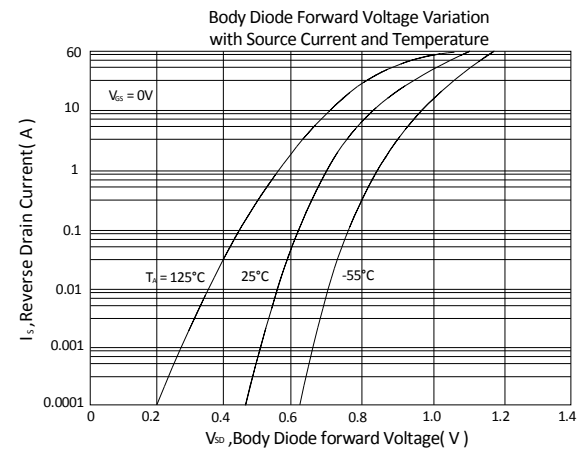
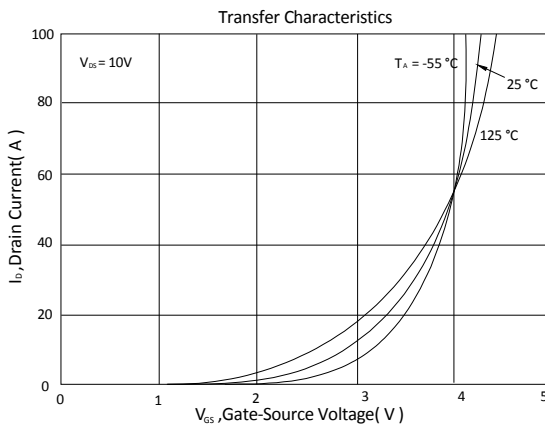
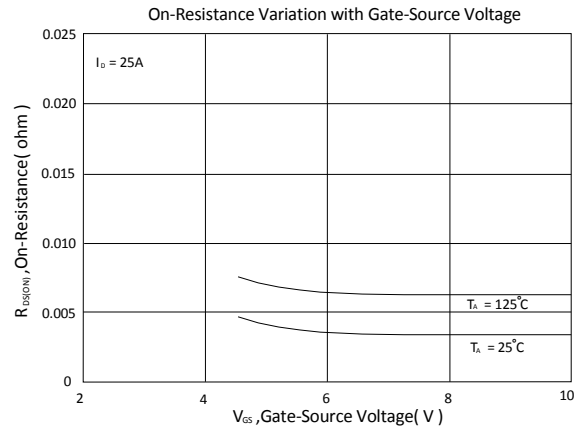
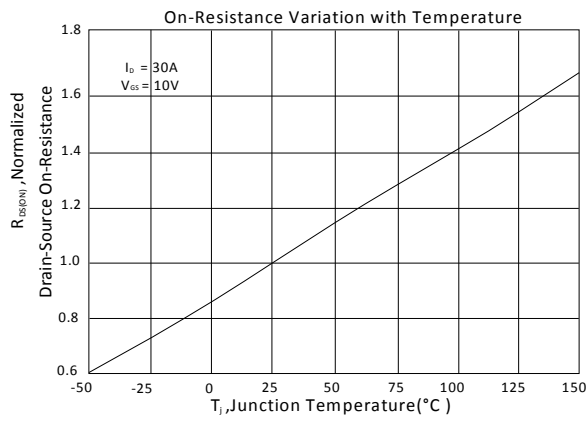
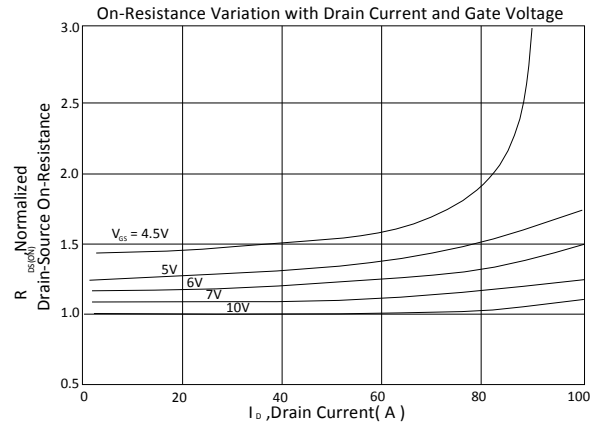
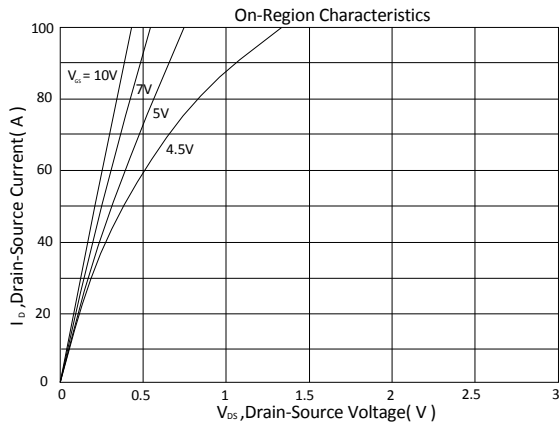
²Independent of operating temperature.

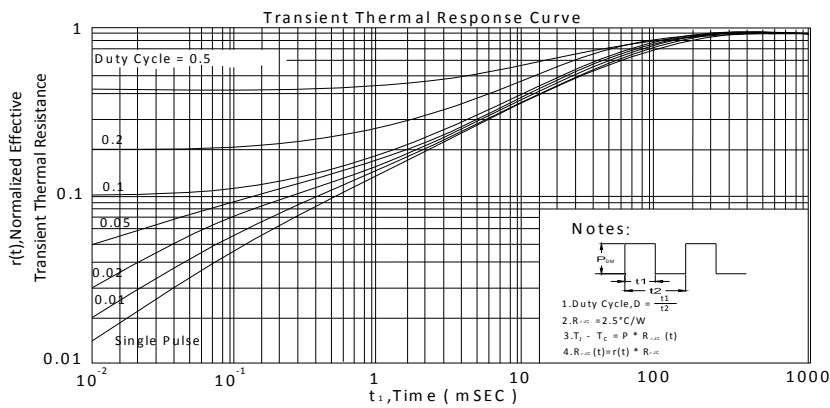
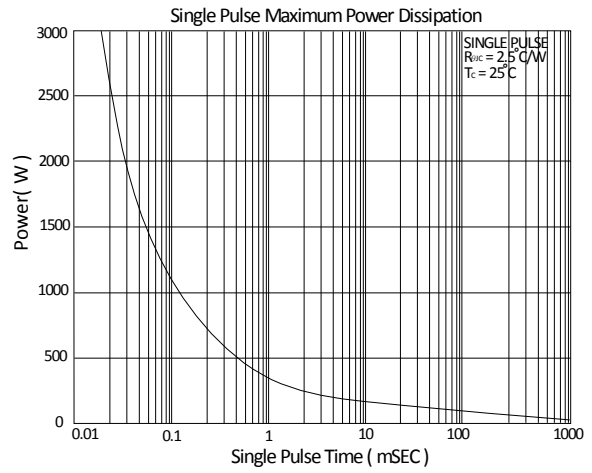
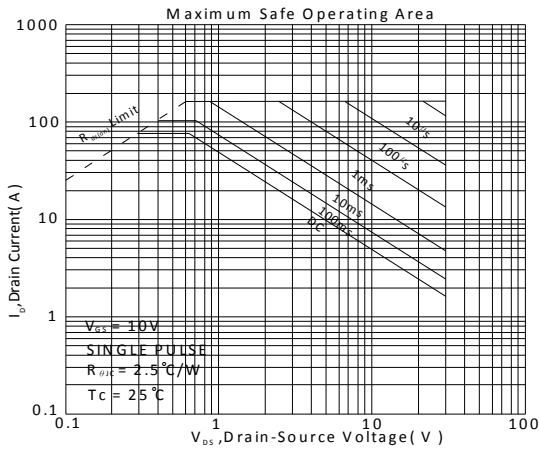
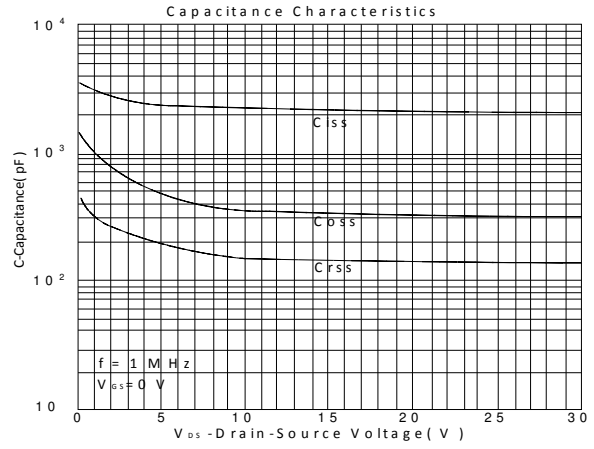
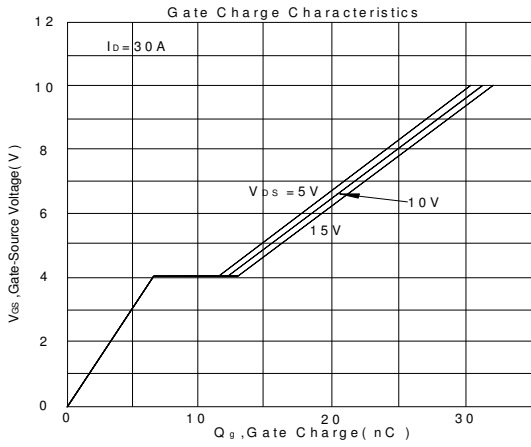
³Pulse width limited by maximum junction temperature.

EMC will review datasheet by quarter, and update new version.



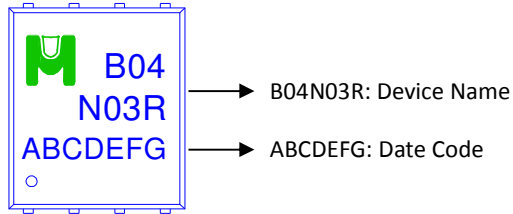
TYPICAL CHARACTERISTICS



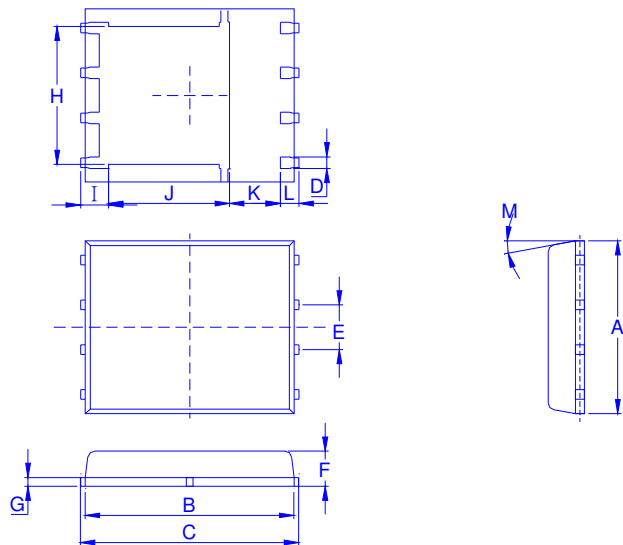


Ordering & Marking Information:

Device Name: EMB04N03HR for EDFN 5 x 6



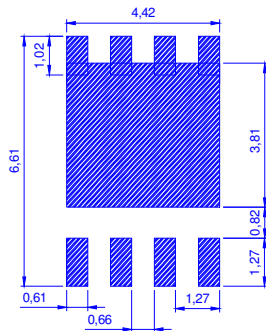
Outline Drawing



Dimension in mm

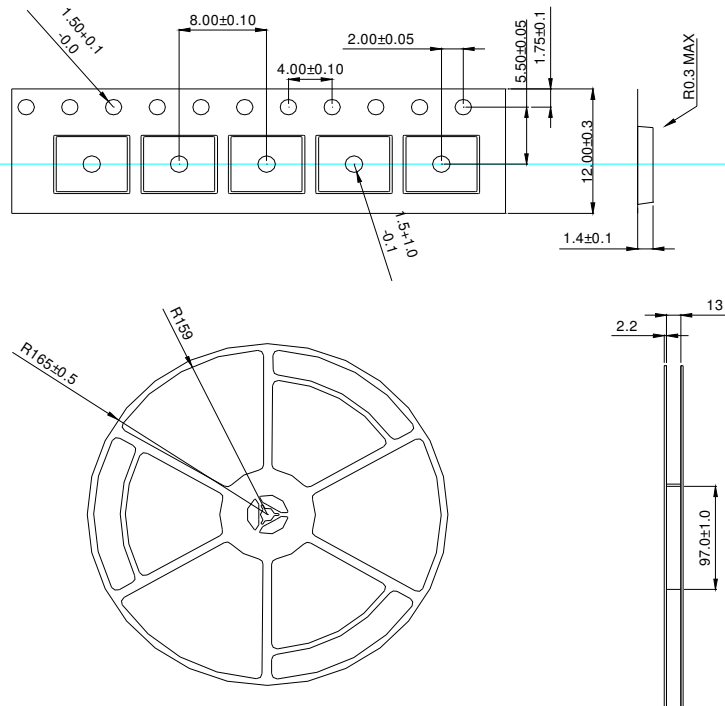
Dimension	A	B	C	D	E	F	G	H	I	J	K	L	M
Min	4.80	5.55	5.90	0.30	1.17	0.85	0.15	3.61	0.38	3.18	1.00	0.38	0°
Typ.	4.90	5.70	6.00	0.40	1.27	0.95	0.20	3.87	0.40	3.44	1.20	0.40	
Max	5.40	5.85	6.15	0.51	1.37	1.17	0.34	4.31	0.71	3.78	1.39	0.71	12°

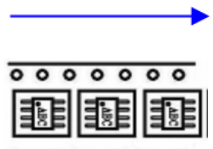
Recommended minimum pads





◆ Tape&Reel Information:2500pcs/Reel(Dimension in millimeter)



產品別	EDFN5X6
Reel 尺寸	13"
編帶方式	FEEED DIRECTION 
前空格	25
後空格	50
裝箱數	
滿卷數量	2.5K
捲/內盒比	1 : 1
內盒滿箱數	2.5K
內/外箱比	10 : 1
外箱滿箱數	25K